



Recent Advances in Thin Film Electronic Devices

Guest Editor:

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Message from the Guest Editor

Thin film electronic devices have been attracting more and more attention because they can be used in many industrial fields, such as flat panel displays, energy devices, sensors, memories, and so on. This Special Issue plans to give an overview of the most recent advances in thin film electronic devices in the abovementioned fields. This Special Issue is aimed at providing selected contributions on advances in the physics, processing, design, characterization, and applications of novel thin film electronic devices. Potential topics include, but are not limited to: thin film transistors; thin film solar cells; thin film sensors; thin film memories; device physics about novel thin film electronic devices; process development of novel devices; characterization of novel thin films and devices; design of novel devices and circuits.





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Message from the Editor-in-Chief

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